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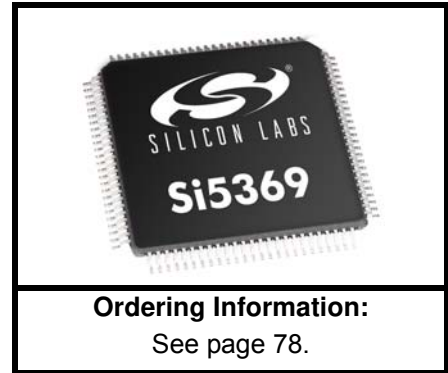
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ANY-FREQUENCY PRECISION CLOCK MULTIPLIER/JITTER ATTENUATOR

Features

- Generates any frequency from 2 kHz to 945 MHz and select frequencies to 1.4 GHz from an input frequency of 2 kHz to 710 MHz
- Ultra-low jitter clock outputs with jitter generation as low as 300 fs rms (12 kHz–20 MHz)
- Integrated loop filter with selectable loop bandwidth (4 Hz to 525 Hz)
- Meets OC-192 GR-253-CORE jitter specifications
- Four clock inputs with manual or automatically controlled hitless switching and phase build-out
- Supports holdover and freerun modes of operation
- SONET frame sync switching and regeneration
- Five clock outputs with selectable signal format (LVPECL, LVDS, CML, CMOS)
- Support for ITU G.709 and custom FEC ratios (253/226, 239/237, 255/238, 255/237, 255/236)
- LOL, LOS, FOS alarm outputs
- Digitally-controlled output phase adjust
- I²C or SPI programmable settings
- On-chip voltage regulator for 1.8 V ±5%, 2.5 V ±10%, or 3.3 V ±10% operation
- Small size: 14 x 14 mm 100-pin TQFP
- Pb-free, RoHS compliant



Applications

- SONET/SDH OC-48/STM-16/OC-192/STM-64 line cards
- GbE/10GbE, 1/2/4/8/10G FC line cards
- ITU G.709 and custom FEC line cards
- Wireless repeaters/wireless backhaul
- Data converter clocking
- OTN/WDM Muxponder, MSPP, ROADM line cards
- SONET/SDH + PDH clock synthesis
- Test and measurement
- Synchronous Ethernet
- Broadcast video

Description

The Si5369 is a jitter-attenuating precision clock multiplier for applications requiring sub 1 ps rms jitter performance. The Si5369 accepts four clock inputs ranging from 2 kHz to 710 MHz and generates five clock outputs ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The device provides virtually any frequency translation combination across this operating range. The outputs are divided down separately from a common source. The Si5369 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. The Si5369 is based on Silicon Laboratories' third-generation DSPLL[®] technology, which provides any-frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The DSPLL loop bandwidth is digitally programmable, providing jitter performance optimization at the application level. Operating from a single 1.8, 2.5, or 3.3 V supply, the Si5369 is ideal for providing clock multiplication and jitter attenuation in high performance timing applications.

Si5369

Functional Block Diagram

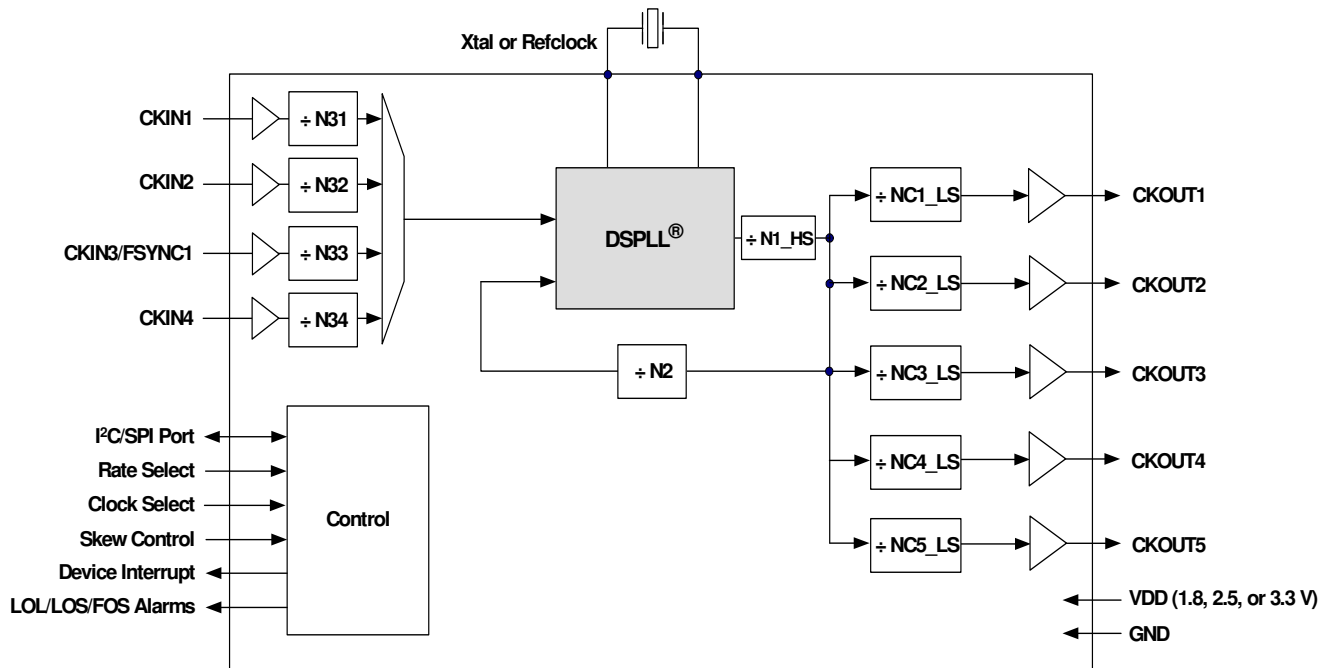


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1. Electrical Specifications

Table 1. Recommended Operating Conditions¹

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Ambient Temperature	T_A		-40	25	85	C
Supply Voltage during Normal Operation	V_{DD}	3.3 V Nominal ²	2.97	3.3	3.63	V
		2.5 V Nominal	2.25	2.5	2.75	V
		1.8 V Nominal	1.71	1.8	1.89	V

Notes:

1. All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise stated.
2. The LVPECL and CMOS output formats draw more current than either LVDS or CML; however, there are restrictions in the allowed output format pin settings so that the maximum power dissipation for the TQFP devices is limited when they are operated at 3.3 V. When there are four enabled LVPECL or CMOS outputs, the fifth output must be disabled. When there are five enabled outputs, there can be no more than three outputs that are either LVPECL or CMOS.

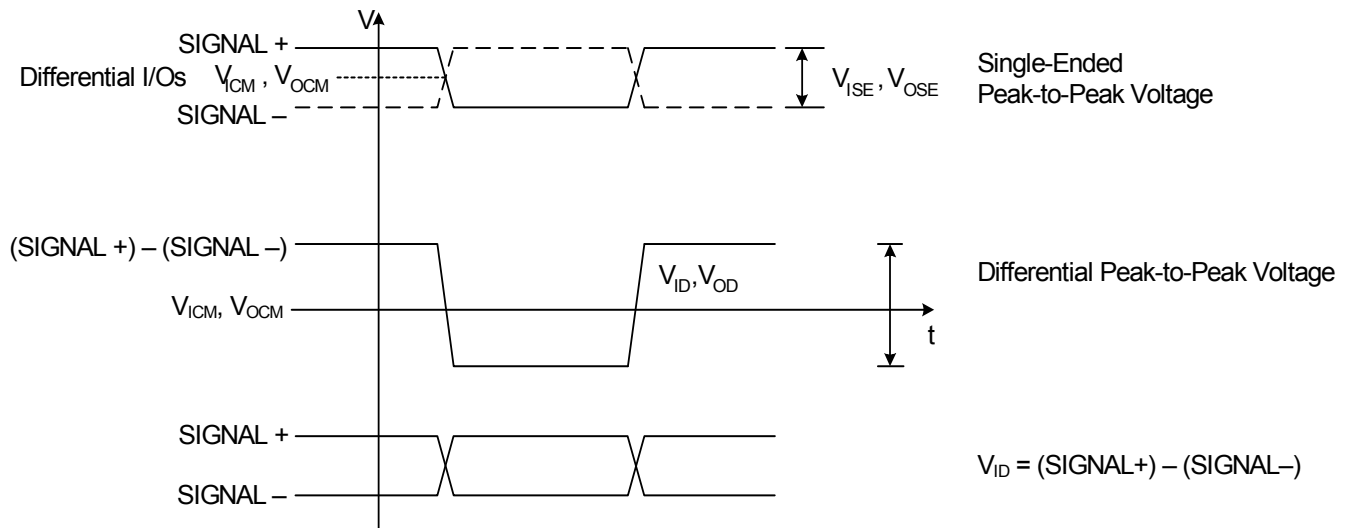


Figure 1. Differential Voltage Characteristics

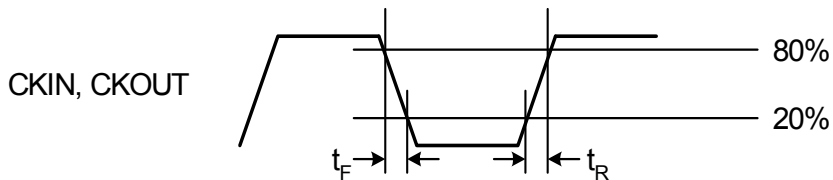


Figure 2. Rise/Fall Time Characteristics

Table 2. DC Characteristics $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V} \pm 10\%, T_A = -40 \text{ to } 85 \text{ }^\circ\text{C})$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply Current ^{1,6}	I_{DD}	LVPECL Format 622.08 MHz Out All CKOUTs Enabled	—	394	435	mA
		LVPECL Format 622.08 MHz Out 1 CKOUT Enabled	—	253	284	mA
		CMOS Format 19.44 MHz Out All CKOUTs Enabled	—	278	400	mA
		CMOS Format 19.44 MHz Out 1 CKOUT Enabled	—	229	261	mA
		Disable Mode	—	165	—	mA
CKINn Input Pins²						
Input Common Mode Voltage (Input Threshold Voltage)	V_{ICM}	1.8 V \pm 5%	0.9	—	1.4	V
		2.5 V \pm 10%	1	—	1.7	V
		3.3 V \pm 10%	1.1	—	1.95	V
Input Resistance	CKN_{RIN}	Single-ended	20	40	60	k Ω
Single-Ended Input Voltage Swing (See Absolute Specs)	V_{ISE}	$f_{CKIN} < 212.5 \text{ MHz}$ See Figure 1.	0.2	—	—	V_{PP}
		$f_{CKIN} > 212.5 \text{ MHz}$ See Figure 1.	0.25	—	—	V_{PP}
Differential Input Voltage Swing (See Absolute Specs)	V_{ID}	$f_{CKIN} < 212.5 \text{ MHz}$ See Figure 1.	0.2	—	—	V_{PP}
		$f_{CKIN} > 212.5 \text{ MHz}$ See Figure 1.	0.25	—	—	V_{PP}

Notes:

1. Current draw is independent of supply voltage
2. No under- or overshoot is allowed.
3. LVPECL outputs require nominal $V_{DD} \geq 2.5 \text{ V}$.
4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
5. LVPECL, CML, LVDS and low-swing LVDS measured with $F_o = 622.08 \text{ MHz}$.
6. The LVPECL and CMOS output formats draw more current than either LVDS or CML; however, there are restrictions in the allowed output format pin settings so that the maximum power dissipation for the TQFP devices is limited when they are operated at 3.3 V. When there are four enabled LVPECL or CMOS outputs, the fifth output must be disabled. When there are five enabled outputs, there can be no more than three outputs that are either LVPECL or CMOS.

Table 2. DC Characteristics (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Clocks (CKOUTn)^{3,5,6}						
Common Mode	CKO _{VCM}	LVPECL 100 Ω load line-to-line	V _{DD} - 1.42	—	V _{DD} - 1.25	V
Differential Output Swing	CKO _{VD}	LVPECL 100 Ω load line-to-line	1.1	—	1.9	V _{PP}
Single Ended Output Swing	CKO _{VSE}	LVPECL 100 Ω load line-to-line	0.5	—	0.93	V _{PP}
Differential Output Voltage	CKO _{VD}	CML 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage	CKO _{VCM}	CML 100 Ω load line-to-line	—	V _{DD} - 0.36	—	V
Differential Output Voltage	CKO _{VD}	LVDS 100 Ω load line-to-line	500	700	900	mV _{PP}
		Low Swing LVDS 100 Ω load line-to-line	350	425	500	mV _{PP}
Common Mode Output Voltage	CKO _{VCM}	LVDS 100 Ω load line-to-line	1.125	1.2	1.275	V
Differential Output Resistance	CKO _{RD}	CML, LVPECL, LVDS	—	200	—	Ω
Output Voltage Low	CKO _{VOLLH}	CMOS	—	—	0.4	V
Output Voltage High	CKO _{VOHLH}	V _{DD} = 1.71 V CMOS	0.8 x V _{DD}	—	—	V

Notes:

1. Current draw is independent of supply voltage
2. No under- or overshoot is allowed.
3. LVPECL outputs require nominal V_{DD} ≥ 2.5 V.
4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details.
5. LVPECL, CML, LVDS and low-swing LVDS measured with F_o = 622.08 MHz.
6. The LVPECL and CMOS output formats draw more current than either LVDS or CML; however, there are restrictions in the allowed output format pin settings so that the maximum power dissipation for the TQFP devices is limited when they are operated at 3.3 V. When there are four enabled LVPECL or CMOS outputs, the fifth output must be disabled. When there are five enabled outputs, there can be no more than three outputs that are either LVPECL or CMOS.

Table 2. DC Characteristics (Continued) $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V} \pm 10\%, T_A = -40 \text{ to } 85 \text{ }^\circ\text{C})$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Drive Current (CMOS driving into CKO_{VOL} for output low or CKO_{VOH} for output high. $CKOUT+$ and $CKOUT-$ shorted externally)	CKO_{IO}	$ICMOS[1:0] = 11$ $V_{DD} = 1.8 \text{ V}$	—	7.5	—	mA
		$ICMOS[1:0] = 10$ $V_{DD} = 1.8 \text{ V}$	—	5.5	—	mA
		$ICMOS[1:0] = 01$ $V_{DD} = 1.8 \text{ V}$	—	3.5	—	mA
		$ICMOS[1:0] = 00$ $V_{DD} = 1.8 \text{ V}$	—	1.75	—	mA
		$ICMOS[1:0] = 11$ $V_{DD} = 3.3 \text{ V}$	—	32	—	mA
		$ICMOS[1:0] = 10$ $V_{DD} = 3.3 \text{ V}$	—	24	—	mA
		$ICMOS[1:0] = 01$ $V_{DD} = 3.3 \text{ V}$	—	16	—	mA
		$ICMOS[1:0] = 00$ $V_{DD} = 3.3 \text{ V}$	—	8	—	mA
2-Level LVCMOS Input Pins						
Input Voltage Low	V_{IL}	$V_{DD} = 1.71 \text{ V}$	—	—	0.5	V
		$V_{DD} = 2.25 \text{ V}$	—	—	0.7	V
		$V_{DD} = 2.97 \text{ V}$	—	—	0.8	V
Input Voltage High	V_{IH}	$V_{DD} = 1.89 \text{ V}$	1.4	—	—	V
		$V_{DD} = 2.25 \text{ V}$	1.8	—	—	V
		$V_{DD} = 3.63 \text{ V}$	2.5	—	—	V
Notes:						
<ol style="list-style-type: none"> Current draw is independent of supply voltage No under- or overshoot is allowed. LVPECL outputs require nominal $V_{DD} \geq 2.5 \text{ V}$. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. LVPECL, CML, LVDS and low-swing LVDS measured with $F_o = 622.08 \text{ MHz}$. The LVPECL and CMOS output formats draw more current than either LVDS or CML; however, there are restrictions in the allowed output format pin settings so that the maximum power dissipation for the TQFP devices is limited when they are operated at 3.3 V. When there are four enabled LVPECL or CMOS outputs, the fifth output must be disabled. When there are five enabled outputs, there can be no more than three outputs that are either LVPECL or CMOS. 						

Table 2. DC Characteristics (Continued)

($V_{DD} = 1.8 \pm 5\%$, $2.5 \pm 10\%$, or $3.3 \text{ V} \pm 10\%$, $T_A = -40$ to $85 \text{ }^\circ\text{C}$)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
3-Level Input Pins⁴						
Input Voltage Low	V_{ILL}		—	—	$0.15 \times V_{DD}$	V
Input Voltage Mid	V_{IMM}		$0.45 \times V_{DD}$	—	$0.55 \times V_{DD}$	V
Input Voltage High	V_{IHH}		$0.85 \times V_{DD}$	—	—	V
Input Low Current	I_{ILL}	See Note 4	-20	—	—	μA
Input Mid Current	I_{IMM}	See Note 4	-2	—	+2	μA
Input High Current	I_{IHH}	See Note 4	—	—	20	μA
LVC MOS Output Pins						
Output Voltage Low	V_{OL}	$I_O = 2 \text{ mA}$ $V_{DD} = 1.71 \text{ V}$	—	—	0.4	V
Output Voltage Low		$I_O = 2 \text{ mA}$ $V_{DD} = 2.97 \text{ V}$	—	—	0.4	V
Output Voltage High	V_{OH}	$I_O = -2 \text{ mA}$ $V_{DD} = 1.71 \text{ V}$	$V_{DD} - 0.4$	—	—	V
Output Voltage High		$I_O = -2 \text{ mA}$ $V_{DD} = 2.97 \text{ V}$	$V_{DD} - 0.4$	—	—	V
Notes:						
<ol style="list-style-type: none"> 1. Current draw is independent of supply voltage 2. No under- or overshoot is allowed. 3. LVPECL outputs require nominal $V_{DD} \geq 2.5 \text{ V}$. 4. This is the amount of leakage that the 3-Level inputs can tolerate from an external driver. See Si53xx Family Reference Manual for more details. 5. LVPECL, CML, LVDS and low-swing LVDS measured with $F_o = 622.08 \text{ MHz}$. 6. The LVPECL and CMOS output formats draw more current than either LVDS or CML; however, there are restrictions in the allowed output format pin settings so that the maximum power dissipation for the TQFP devices is limited when they are operated at 3.3 V. When there are four enabled LVPECL or CMOS outputs, the fifth output must be disabled. When there are five enabled outputs, there can be no more than three outputs that are either LVPECL or CMOS. 						

Table 3. AC Specifications $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V} \pm 10\%, T_A = -40 \text{ to } 85 \text{ }^\circ\text{C})$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Single-Ended Reference Clock Input Pin XA (XB with cap to GND)						
Input Resistance	XA_{RIN}	RATE[1:0] = LM, MH, ac coupled	—	12	—	$k\Omega$
Input Voltage Swing	XA_{VPP}	RATE[1:0] = LM, MH, ac coupled	0.5	—	1.2	V_{PP}
Differential Reference Clock Input Pins (XA/XB)						
Input Voltage Swing	XA/XB_{VPP}	RATE[1:0] = LM, MH	0.5	—	2.4	V_{PP}
CKINn Input Pins						
Input Frequency	CKN_F		0.002	—	710	MHz
Input Duty Cycle (Minimum Pulse Width)	CKN_{DC}	Whichever is smaller (i.e., the 40% / 60% limitation applies only to high frequency clocks)	40	—	60	%
			2	—	—	ns
Input Capacitance	CKN_{CIN}		—	—	3	pF
Input Rise/Fall Time	CKN_{TRF}	20–80% See Figure 2	—	—	11	ns
CKOUTn Output Pins						
(See ordering section for speed grade vs frequency limits)						
Output Frequency (Output not config- ured for CMOS or Disabled)	CKO_F	$N1 \geq 6$	0.002	—	945	MHz
		$N1 = 5$	970	—	1134	MHz
		$N1 = 4$	1.213	—	1.4	GHz
Maximum Output Frequency in CMOS Format	CKO_F		—	—	212.5	MHz
Output Rise/Fall (20–80 %) @ 622.08 MHz output	CKO_{TRF}	Output not configured for CMOS or Disabled See Figure 2	—	230	350	ps
Notes:						
1. Input to output phase skew after an ICAL is not controlled and can assume any value.						
2. Lock and settle time performance is dependent on the frequency plan and the XAXB reference frequency. Please visit the Silicon Labs Technical Support web page at: https://www.silabs.com/support/pages/contacttechnicalsupport.aspx to submit a technical support request regarding the lock time of your frequency plan.						

Table 3. AC Specifications (Continued) $(V_{DD} = 1.8 \pm 5\%, 2.5 \pm 10\%, \text{ or } 3.3 \text{ V} \pm 10\%, T_A = -40 \text{ to } 85 \text{ }^\circ\text{C})$

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO_{TRF}	CMOS Output $V_{DD} = 1.71$ $C_{LOAD} = 5 \text{ pF}$	—	—	8	ns
Output Rise/Fall (20–80%) @ 212.5 MHz output	CKO_{TRF}	CMOS Output $V_{DD} = 2.97$ $C_{LOAD} = 5 \text{ pF}$	—	—	2	ns
Output Duty Cycle Uncertainty @ 622.08 MHz	CKO_{DC}	100 Ω Load Line-to-Line Measured at 50% Point (Not for CMOS)	—	—	± 40	ps
LVC MOS Input Pins						
Minimum Reset Pulse Width	t_{RSTMN}		1	—		μs
Reset to Microprocessor Access Ready	t_{READY}		—	—	10	ms
Input Capacitance	C_{in}		—	—	3	pF
LVC MOS Output Pins						
Rise/Fall Times	t_{RF}	$C_{LOAD} = 20\text{pf}$ See Figure 2	—	25	—	ns
LOSn Trigger Window	LOS_{TRIG}	From last $CKIN_n \uparrow$ to \downarrow Internal detection of LOSn $N3 \neq 1$	—	—	$4.5 \times N3$	T_{CKIN}
Time to Clear LOL after LOS Cleared	t_{CLRLOL}	\downarrow LOS to \downarrow LOL Fold = Fnew Stable Xa/XB reference	—	10	—	ms
Device Skew						
Output Clock Skew	t_{SKEW}	\uparrow of $CKOUT_n$ to \uparrow of $CKOUT_m$, $CKOUT_n$ and $CKOUT_m$ at same frequency and signal format <u>PHASEOFFSET = 0</u> <u>CKOUT_ALWAYS_ON = 1</u> <u>SQ_ICAL = 1</u>	—	—	100	ps
Notes:						
1. Input to output phase skew after an ICAL is not controlled and can assume any value.						
2. Lock and settle time performance is dependent on the frequency plan and the XAXB reference frequency. Please visit the Silicon Labs Technical Support web page at: https://www.silabs.com/support/pages/contacttechnicalsupport.aspx to submit a technical support request regarding the lock time of your frequency plan.						

Table 3. AC Specifications (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Phase Change due to Temperature Variation ¹	t _{TEMP}	Max phase changes from -40 to +85 °C	—	300	500	ps
PLL Performance (f _{in} = f _{out} = 622.08 MHz; BW = 7 Hz; LVPECL, XAXB = 114.285 MHz)						
Lock Time ²	t _{LOCKMP}	Start of ICAL to ↓ of LOL	—	0.8	1.0	s
Settle Time ²	t _{SETTLE}	Start of ICAL to F _{OUT} within 5 ppm of final value	—	4.2	5.0	s
Output Clock Phase Change	t _{P_STEP}	After clock switch f ₃ ≥ 128 kHz	—	200	—	ps
Closed Loop Jitter Peaking	J _{PK}		—	0.05	0.1	dB
Jitter Tolerance	J _{TOL}	Jitter Frequency ≥ Loop Bandwidth	5000/BW	—	—	ns pk-pk
Phase Noise f _{out} = 622.08 MHz	CKO _{PN}	100 Hz Offset	—	-95	—	dBc/Hz
		1 kHz Offset	—	-110	—	dBc/Hz
		10 kHz Offset	—	-117	—	dBc/Hz
		100 kHz Offset	—	-118	—	dBc/Hz
		1 MHz Offset	—	-131	—	dBc/Hz
Spurious Noise	SP _{SPUR}	Max spur @ n x F ₃ (n ≥ 1, n x F ₃ < 100 MHz)	—	-67	—	dBc
Notes:						
1. Input to output phase skew after an ICAL is not controlled and can assume any value.						
2. Lock and settle time performance is dependent on the frequency plan and the XAXB reference frequency. Please visit the Silicon Labs Technical Support web page at: https://www.silabs.com/support/pages/contacttechnicalsupport.aspx to submit a technical support request regarding the lock time of your frequency plan.						

Table 4. Microprocessor Control

($V_{DD} = 1.8 \pm 5\%$, $2.5 \pm 10\%$, or $3.3 \text{ V} \pm 10\%$, $T_A = -40$ to $85 \text{ }^\circ\text{C}$)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
I²C Bus Lines (SDA, SCL)						
Input Voltage Low	$V_{IL_{I2C}}$		—	—	$0.25 \times V_{DD}$	V
Input Voltage High	$V_{IH_{I2C}}$		$0.7 \times V_{DD}$	—	V_{DD}	V
Hysteresis of Schmitt trigger inputs	$V_{HYS_{I2C}}$	$V_{DD} = 1.8 \text{ V}$	$0.1 \times V_{DD}$	—	—	V
		$V_{DD} = 2.5$ or 3.3 V	$0.05 \times V_{DD}$	—	—	V
Output Voltage Low	$V_{OL_{I2C}}$	$V_{DD} = 1.8 \text{ V}$ $I_O = 3 \text{ mA}$	—	—	$0.2 \times V_{DD}$	V
		$V_{DD} = 2.5$ or 3.3 V $I_O = 3 \text{ mA}$	—	—	0.4	V

Table 4. Microprocessor Control (Continued)(V_{DD} = 1.8 ± 5%, 2.5 ± 10%, or 3.3 V ± 10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
SPI Specifications						
Duty Cycle, SCLK	t _{DC}	SCLK = 10 MHz	40	—	60	%
Cycle Time, SCLK	t _C		100	—	—	ns
Rise Time, SCLK	t _r	20–80%	—	—	25	ns
Fall Time, SCLK	t _f	20–80%	—	—	25	ns
Low Time, SCLK	t _{lsc}	20–20%	30	—	—	ns
High Time, SCLK	t _{hsc}	80–80%	30	—	—	ns
Delay Time, SCLK Fall to SDO Active	t _{d1}		—	—	25	ns
Delay Time, SCLK Fall to SDO Transition	t _{d2}		—	—	25	ns
Delay Time, SS Rise to SDO Tri-state	t _{d3}		—	—	25	ns
Setup Time, SS to SCLK Fall	t _{su1}		25	—	—	ns
Hold Time, SS to SCLK Rise	t _{h1}		20	—	—	ns
Setup Time, SDI to SCLK Rise	t _{su2}		25	—	—	ns
Hold Time, SDI to SCLK Rise	t _{h2}		20	—	—	ns
Delay Time between Slave Selects	t _{cs}		25	—	—	ns

Table 5. Jitter Generation

Parameter	Symbol	Test Condition*		Min	Typ	Max	GR-253-Specification	Unit
		Measurement Filter	DSPLL BW ²					
Jitter Gen OC-192	JGEN	0.02–80 MHz	120 Hz	—	4.2	—	30	ps _{pp}
				—	.27	—	N/A	ps _{rms}
		4–80 MHz	120 Hz	—	3.7	—	10	ps _{pp}
				—	.14	—	N/A	ps _{rms}
		0.05–80 MHz	120 Hz	—	4.4	—	10	ps _{pp}
				—	.26	—	1.0	ps _{rms}
Jitter Gen OC-48	JGEN	0.12–20 MHz	120 Hz	—	3.5	—	40.2	ps _{pp}
				—	.27	—	4.02	ps _{rms}

***Note:** Test conditions:
 1. f_{IN} = f_{OUT} = 622.08 MHz
 2. Clock input: LVPECL
 3. Clock output: LVPECL
 4. PLL bandwidth: 120 Hz
 5. 114.285 MHz 3rd OT crystal used as XA/XB input
 6. V_{DD} = 2.5 V
 7. T_A = 85 °C
 8. Jitter integration bands include low-pass (-20 dB/dec) and high-pas (-60 dB/dec) roll-offs per Telecordia GR-253-CORE.

Table 6. Thermal Characteristics(V_{DD} = 1.8 ±5%, 2.5 ±10%, or 3.3 V ±10%, T_A = -40 to 85 °C)

Parameter	Symbol	Test Condition	Value	Unit
Thermal Resistance Junction to Ambient	θ_{JA}	Still Air	31	°C/W

Table 7. Absolute Maximum Ratings*

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DC Supply Voltage	V _{DD}		-0.5	—	3.8	V
LVC MOS Input Voltage	V _{DIG}		-0.3	—	V _{DD} +0.3	V
CKINn Voltage Level Limits	CKN _{VIN}		0	—	V _{DD}	V
XA/XB Voltage Level Limits	XA _{VIN}		0	—	1.2	V
Operating Junction Temperature	T _{JCT}		-55	—	150	°C
Storage Temperature Range	T _{STG}		-55	—	150	°C
ESD HBM Tolerance (100 pF, 1.5 kΩ); All pins except CKIN+/CKIN-			2	—	—	kV
ESD MM Tolerance; All pins except CKIN+/CKIN-			150	—	—	V
ESD HBM Tolerance (100 pF, 1.5 kΩ); CKIN+/CKIN-			700	—	—	V
ESD MM Tolerance; CKIN+/CKIN-			100	—	—	V
Latch-up Tolerance			JESD78 Compliant			
<p>*Note: Permanent device damage may occur if the Absolute Maximum Ratings are exceeded. Functional operation should be restricted to the conditions as specified in the operation sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability.</p>						

2. Typical Phase Noise Performance

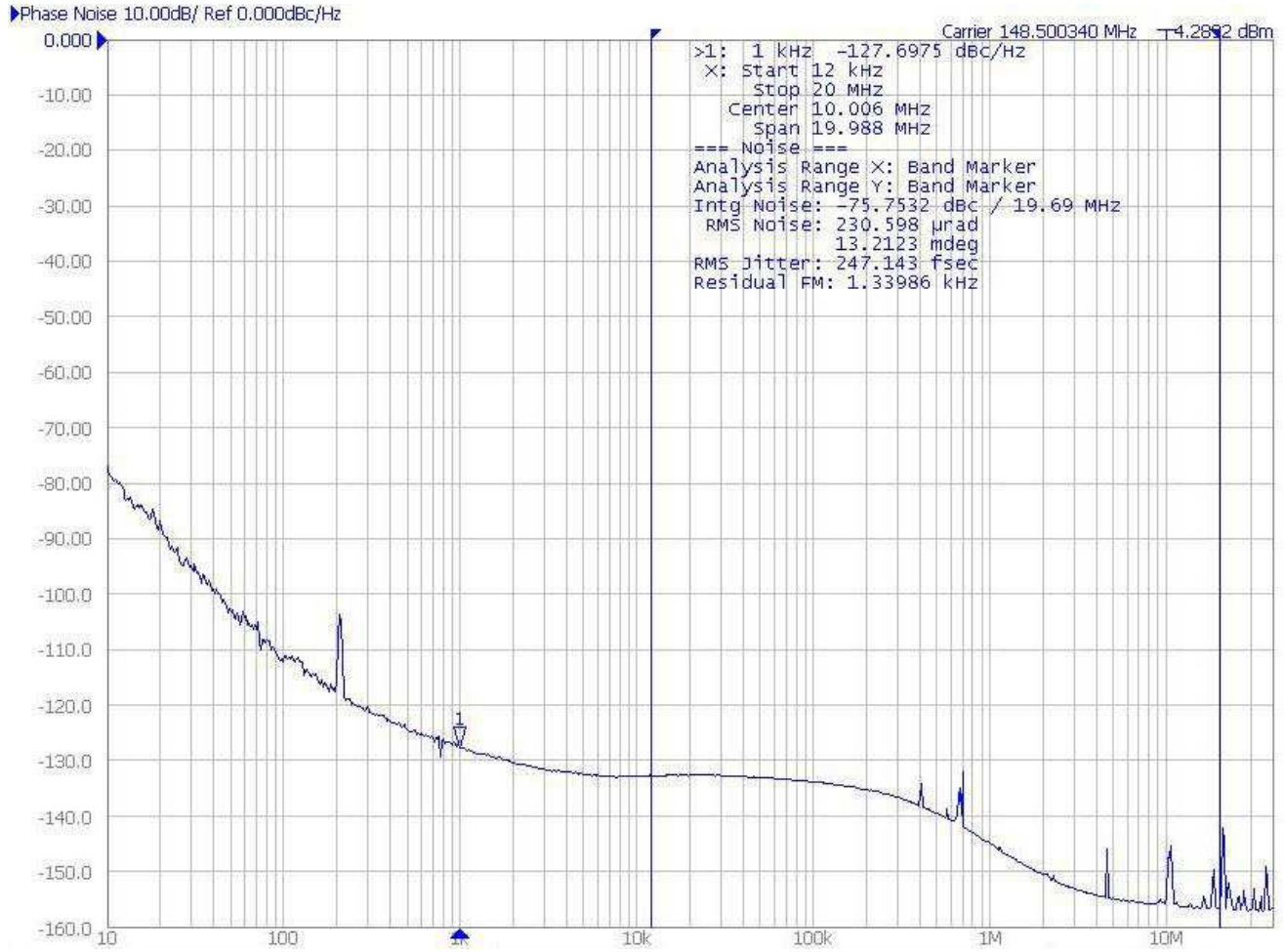


Figure 3. Broadcast Video*

*Note: Phase noise plot RMS jitter value used brick wall integration.

Jitter Bandwidth	Jitter (peak-peak)	Jitter (RMS)
10 Hz to 20 MHz	5.24 ps	484
Note: Number of samples: 8.91E9		

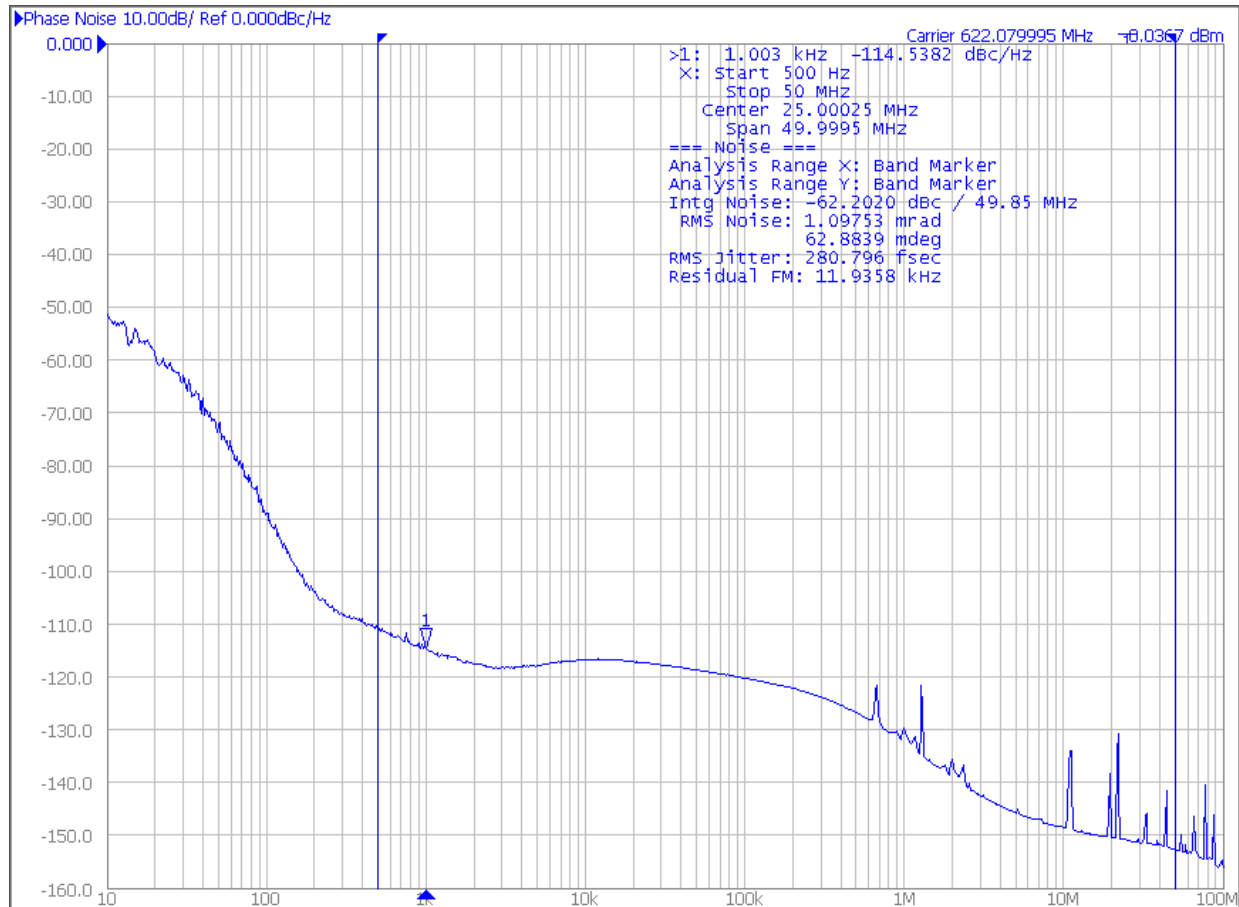


Figure 4. OTN/SONET/SDH Phase Noise*

*Note: Phase noise plot RMS jitter value uses brick wall integration.

Jitter Bandwidth	Jitter, RMS
SONET_OC48, 12 kHz to 20 MHz	266 fs
SONET_OC192_A, 20 kHz to 80 MHz	283 fs
SONET_OC192_B, 4 MHz to 80 MHz	155 fs
SONET_OC192_C, 50 kHz to 80 MHz	275 fs
Brick Wall_800 Hz to 80 MHz	287 fs

Note: Jitter integration bands include low-pass (-20 dB/Dec) and hi-pass (-60 dB/Dec) roll-offs per Telecordia GR-253-CORE.

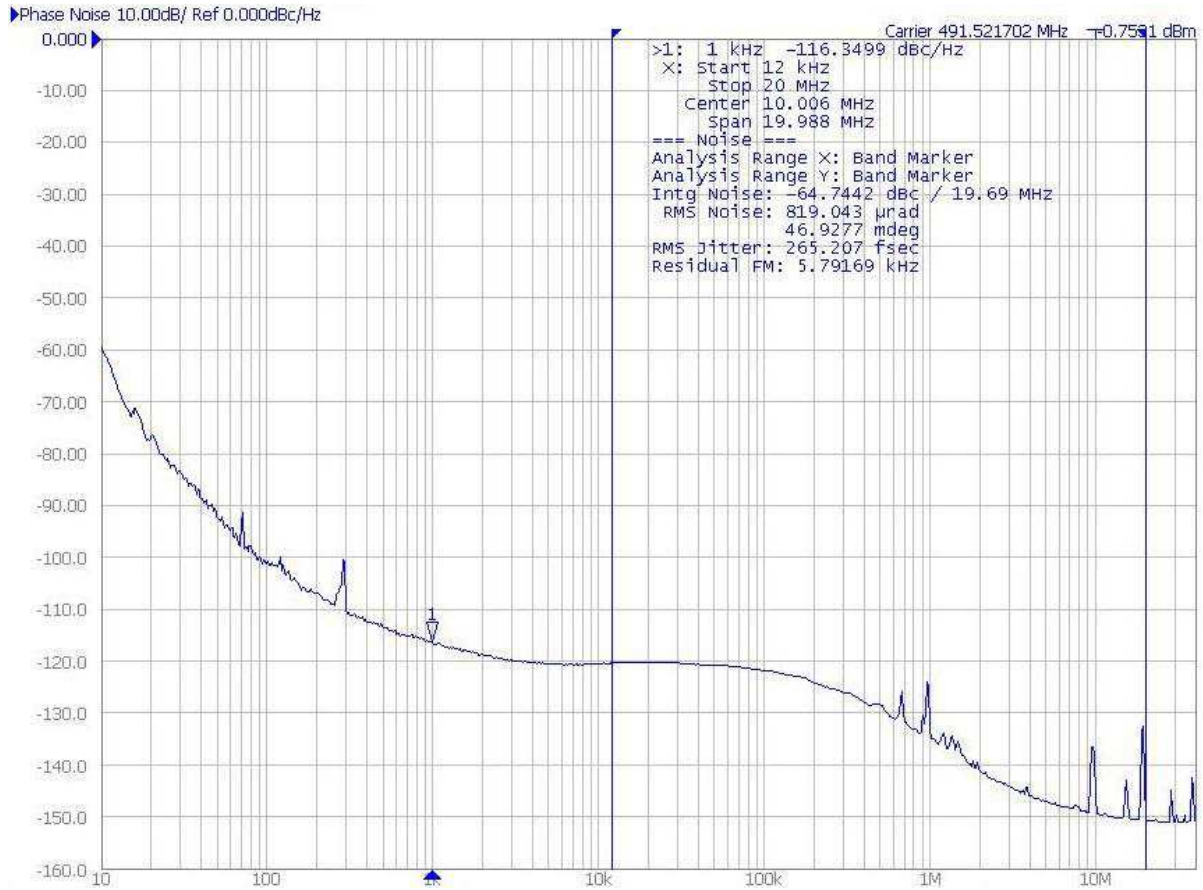


Figure 5. Wireless Base Station Phase Noise*

*Note: Phase noise plot RMS jitter value uses brick wall integration.

Jitter Bandwidth	Jitter (peak-peak)	Jitter (RMS)
10 Hz to 20 MHz	7.28 ps	581
Note: Number of samples: 8.91E9		

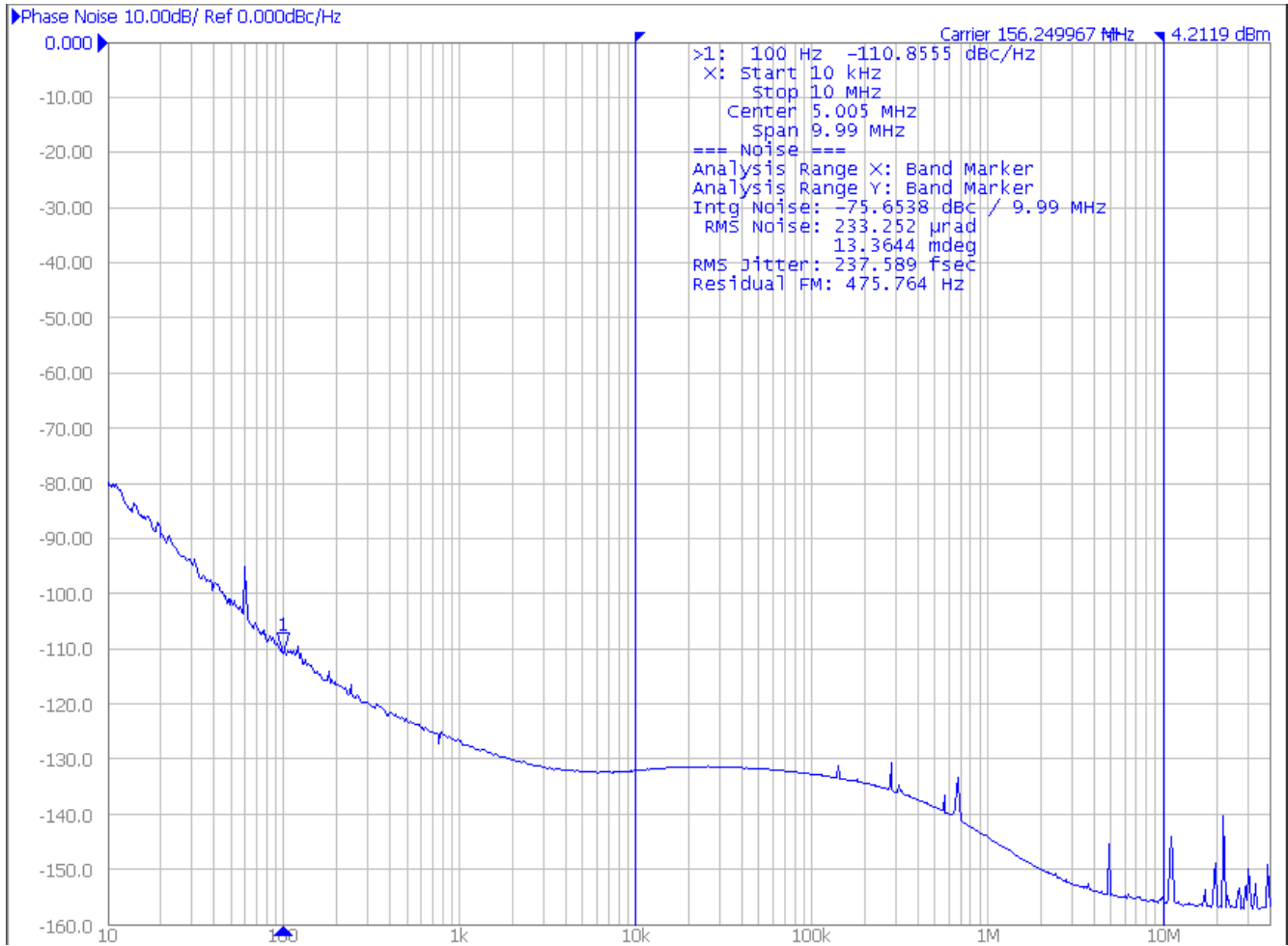


Figure 6. 10 GbE Phase Noise*

*Note: Phase noise plot RMS jitter value uses brick wall integration.

Jitter Bandwidth	Jitter (RMS)
10 kHz to 10 MHz	238 fs

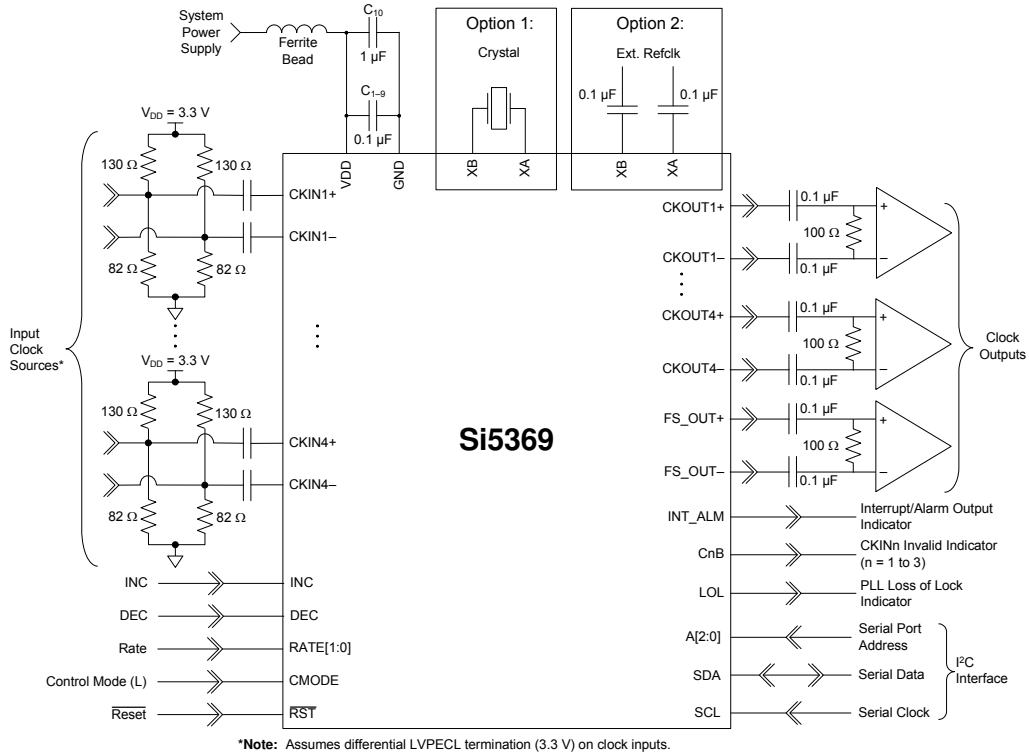


Figure 7. Si5369 Typical Application Circuit (I²C Control Mode)

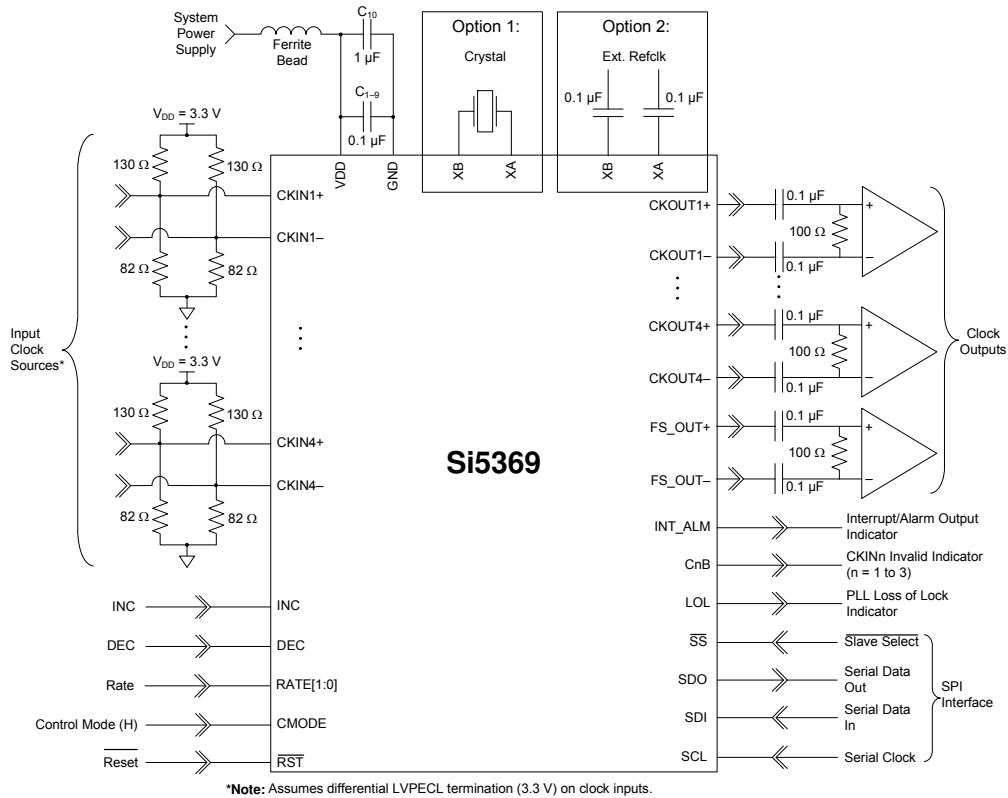


Figure 8. Si5369 Typical Application Circuit (SPI Control Mode)

3. Functional Description

The Si5369 is a jitter-attenuating precision clock multiplier for applications requiring sub 1 ps rms jitter performance. The Si5369 accepts four clock inputs ranging from 2 kHz to 710 MHz and generates five clock outputs ranging from 2 kHz to 945 MHz and select frequencies to 1.4 GHz. The device provides virtually any frequency translation combination across this operating range. Independent dividers are available for every input clock and output clock, so the Si5369 can accept input clocks at different frequencies and it can generate output clocks at different frequencies. The Si5369 input clock frequency and clock multiplication ratio are programmable through an I²C or SPI interface. Optionally, the fifth clock output can be configured as a 2 to 512 kHz SONET/SDH frame synchronization output that is phase aligned with one of the high-speed output clocks. Silicon Laboratories offers a PC-based software utility, *DSPLLsim*, that can be used to determine the optimum PLL divider settings for a given input frequency/clock multiplication ratio combination that minimizes phase noise and power consumption. This utility can be downloaded from <http://www.silabs.com/timing> (click on Documentation).

The Si5369 is based on Silicon Laboratories' 3rd-generation DSPLL[®] technology, which provides any-frequency synthesis and jitter attenuation in a highly integrated PLL solution that eliminates the need for external VCXO and loop filter components. The Si5369 PLL loop bandwidth is digitally programmable and supports a range from 4 to 525 Hz. The *DSPLLsim* software utility can be used to calculate valid loop bandwidth settings for a given input clock frequency/clock multiplication ratio.

The Si5369 supports hitless switching between input clocks in compliance with GR-253-CORE and GR-1244-CORE that greatly minimizes the propagation of phase transients to the clock outputs during an input clock transition (<200 ps typ). Manual, automatic revertive and non-revertive input clock switching options are available. The Si5369 monitors the four input clocks for loss-of-signal and provides a LOS alarm when it detects missing pulses on any of the four input clocks. The device monitors the lock status of the PLL. The lock detect algorithm works by continuously monitoring the phase of the input clock in relation to the phase of the feedback clock. The Si5369 monitors the frequency of CKIN1, CKIN2, CKIN3, and CKIN4 with respect to a selected reference frequency and generates a frequency offset alarm (FOS) if the threshold is exceeded. This FOS feature is available for SONET applications in which both the monitored frequency on CKIN1, CKIN3, and CKIN4 and the reference frequency are integer multiples of 19.44 MHz. Both Stratum 3/3E and SONET Minimum Clock (SMC) FOS thresholds are supported.

The Si5369 provides a digital hold capability that allows the device to continue generation of a stable output clock when the selected input reference is lost. During digital hold, the DSPLL generates an output frequency based on

a historical average that existed a fixed amount of time before the error event occurred, eliminating the effects of phase and frequency transients that may occur immediately preceding digital hold.

The Si5369 has five differential clock outputs. The electrical format of the clock outputs is programmable to support LVPECL, LVDS, CML, or CMOS loads. If not required, unused clock outputs can be powered down to minimize power consumption. The phase difference between the selected input clock and the output clocks is adjustable in 200 ps increments for system skew control. In addition, the phase of one output clock may be adjusted in relation to the phase of the other output clock. The resolution varies from 800 ps to 2.2 ns depending on the PLL divider settings. Consult the *DSPLLsim* configuration software to determine the phase offset resolution for a given input clock/clock multiplication ratio combination. For system-level debugging, a bypass mode is available which drives the output clock directly from the input clock, bypassing the internal DSPLL. The device is powered by a single 1.8, 2.5, or 3.3 V supply.

3.1. External Reference

An external clock or a low-cost 114.285 MHz 3rd overtone crystal is typically used as part of a fixed-frequency oscillator within the DSPLL. This external reference is required for the device to operate. Silicon Laboratories recommends using a high-quality crystal. Specific recommendations may be found in the Family Reference Manual. An external clock from a high-quality OCXO or TCXO can also be used as a reference for the device.

If there is a need to use a reference oscillator instead of a crystal, Silicon Labs does not recommend using MEMS based oscillators. Instead, Silicon Labs recommends the Si530EB121M109DG, which is a very low jitter/wander, LVPECL, 2.5 V crystal oscillator. The very low loop BW of the Si5369 means that it can be susceptible to XAXB reference sources that have high wander. Experience has shown that in spite of having low jitter, some MEMs oscillators have high wander, and these devices should be avoided. Contact Silicon Labs for details.

In digital hold, the DSPLL remains locked to this external reference. Any changes in the frequency of this reference when the DSPLL is in digital hold, will be tracked by the output of the device. Note that crystals can have temperature sensitivities.

3.2. Further Documentation

Consult the Silicon Laboratories Any-Frequency Precision Clock Family Reference Manual (FRM) for detailed information about the Si5369. Additional design support is available from Silicon Laboratories through your distributor.

Silicon Laboratories has developed a PC-based software utility called *DSPLLsim* to simplify device configuration, frequency planning, and loop bandwidth selection. The FRM and this utility can be downloaded from <http://www.silabs.com/timing>; click on Documentation.

4. Register Map

All register bits that are not defined in this map should always be written with the specified Reset Values. The writing to these bits of values other than the specified Reset Values may result in undefined device behavior. Registers not listed, such as Register 64, should never be written to.

Register	D7	D6	D5	D4	D3	D2	D1	D0
0		FREE_RUN	CKOUT_ALWAYS_ON				BYPASS_REG	
1	CK_PRIOR4 [1:0]		CK_PRIOR3 [1:0]		CK_PRIOR2 [1:0]		CK_PRIOR1 [1:0]	
2	BWSEL_REG [3:0]							
3	CKSEL_REG [1:0]		DHOLD	SQ_ICAL				
4	AUTOSEL_REG [1:0]			HIST_DEL [4:0]				
5	ICMOS [1:0]		SFOUT2_REG [2:0]			SFOUT1_REG [2:0]		
6			SFOUT4_REG [2:0]			SFOUT3_REG [2:0]		
7			SFOUT5_REG [2:0]			FOSREFSEL [2:0]		
8	HLOG_4 [1:0]		HLOG_3 [1:0]		HLOG_2 [1:0]		HLOG_1 [1:0]	
9	HIST_AVG [4:0]						HLOG_5 [1:0]	
10			DSBL5_REG		DSBL4_REG	DSBL3_REG	DSBL2_REG	DSBL1_REG
11					PD_CK4	PD_CK3	PD_CK2	PD_CK1
19	FOS_EN	FOS_THR [1:0]		VALTIME [1:0]		LOCKT [2:0]		
20			ALR-MOUT_PIN	CK3_BAD_PIN	CK2_BAD_PIN	CK1_BAD_PIN	LOL_PIN	INT_PIN
21				CK4_ACTV_PIN	CK3_ACTV_PIN	CK2_ACTV_PIN	CK1_ACTV_PIN	CKSEL_PIN
22					CK_ACTV_POL	CK_BAD_POL	LOL_POL	INT_POL
23				LOS4_MSK	LOS3_MSK	LOS2_MSK	LOS1_MSK	LOSX_MSK
24				FOS4_MSK	FOS3_MSK	FOS2_MSK	FOS1_MSK	LOL_MSK
25	N1_HS [2:0]				NC1_LS [19:16]			
26	NC1_LS [15:8]							
27	NC1_LS [7:0]							
28					NC2_LS [19:16]			
29	NC2_LS [15:8]							
30	NC2_LS [7:0]							
31					NC3_LS [19:16]			

Register	D7	D6	D5	D4	D3	D2	D1	D0
32	NC3_LS [15:8]							
33	NC3_LS [7:0]							
34					NC4_LS [19:16]			
35	NC4_LS [15:8]							
36	NC4_LS [7:0]							
37					NC5_LS [19:16]			
38	NC5_LS [15:8]							
39	NC5_LS [7:0]							
40	N2_HS [2:0]				N2_LS [19:16]			
41	N2_LS [15:8]							
42	N2_LS [7:0]							
43					N31_ [18:16]			
44	N31_ [15:8]							
45	N31_ [7:0]							
46					N32_ [18:16]			
47	N31_ [15:8]							
48	N32_ [7:0]							
49					N33_ [18:16]			
50	N33_ [15:8]							
51	N33_ [7:0]							
52					N34_ [18:16]			
53	N34_ [15:8]							
54	N34_ [7:0]							
55			CLKIN2RATE_ [2:0]			CLKIN1RATE [2:0]		
56			CLKIN4RATE_ [2:0]			CLKIN3RATE [2:0]		
128					CK4_ACT-V_REG	CK3_ACT-V_REG	CK2_ACT-V_REG	CK1_ACT-V_REG
129				LOS4_INT	LOS3_INT	LOS2_INT	LOS1_INT	LOSX_INT
130		DIGHOLD-VALID		FOS4_INT	FOS3_INT	FOS2_INT	FOS1_INT	LOL_INT
131				LOS4_FLG	LOS3_FLG	LOS2_FLG	LOS1_FLG	LOSX_FLG

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Register	D7	D6	D5	D4	D3	D2	D1	D0
132			FOS4_FLG	FOS3_FLG	FOS2_FLG	FOS1_FLG	LOL_FLG	
134	PARTNUM_RO [11:4]							
135	PARTNUM_RO [3:0]				REVID_RO [3:0]			
136	RST_REG	ICAL						
137								FASTLOCK
138					LOS4_EN [1:1]	LOS3_EN [1:1]	LOS2_EN [1:1]	LOS1_EN [1:1]
139	LOS4_EN [0:0]	LOS3_EN [0:0]	LOS2_EN [0:0]	LOS1_EN [0:0]	FOS4_EN	FOS3_EN	FOS2_EN	FOS1_EN
140	INDEPENDENTSKEW1 [7:0]							
141	INDEPENDENTSKEW2 [7:0]							
142	INDEPENDENTSKEW3 [7:0]							
143	INDEPENDENTSKEW4 [7:0]							
144	INDEPENDENTSKEW5 [7:0]							

5. Register Descriptions

Register 0.

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Name		FREE_RUN	CKOUT_ALWAYS_ON				BYPASS_REG	
Type	R	R/W	R/W	R	R	R	R/W	R

Reset value = 0001 0100

Bit	Name	Function
7	Reserved	
6	FREE_RUN	Free Run. Internal to the device, route XA/XB to CKIN2. This allows the device to lock to its external reference. 0: Disable Free Run 1: Enable
5	CKOUT_ALWAYS_ON	CKOUT Always On. This will bypass the SQ_ICAL function. Output will be available even if SQ_ICAL is on and ICAL is not complete or successful. See Table 8. 0: Squelch output until part is calibrated (ICAL). 1: Provide an output. Note: The frequency may be significantly off until the part is calibrated.
4:2	Reserved	
1	BYPASS_REG	Bypass Register. This bit enables or disables the PLL bypass mode. Use is only valid when the part is in digital hold or before the first ICAL. 0: Normal operation 1: Bypass mode. Selected input clock is connected to CKOUT buffers, bypassing PLL.
0	Reserved	